

Descripción del producto

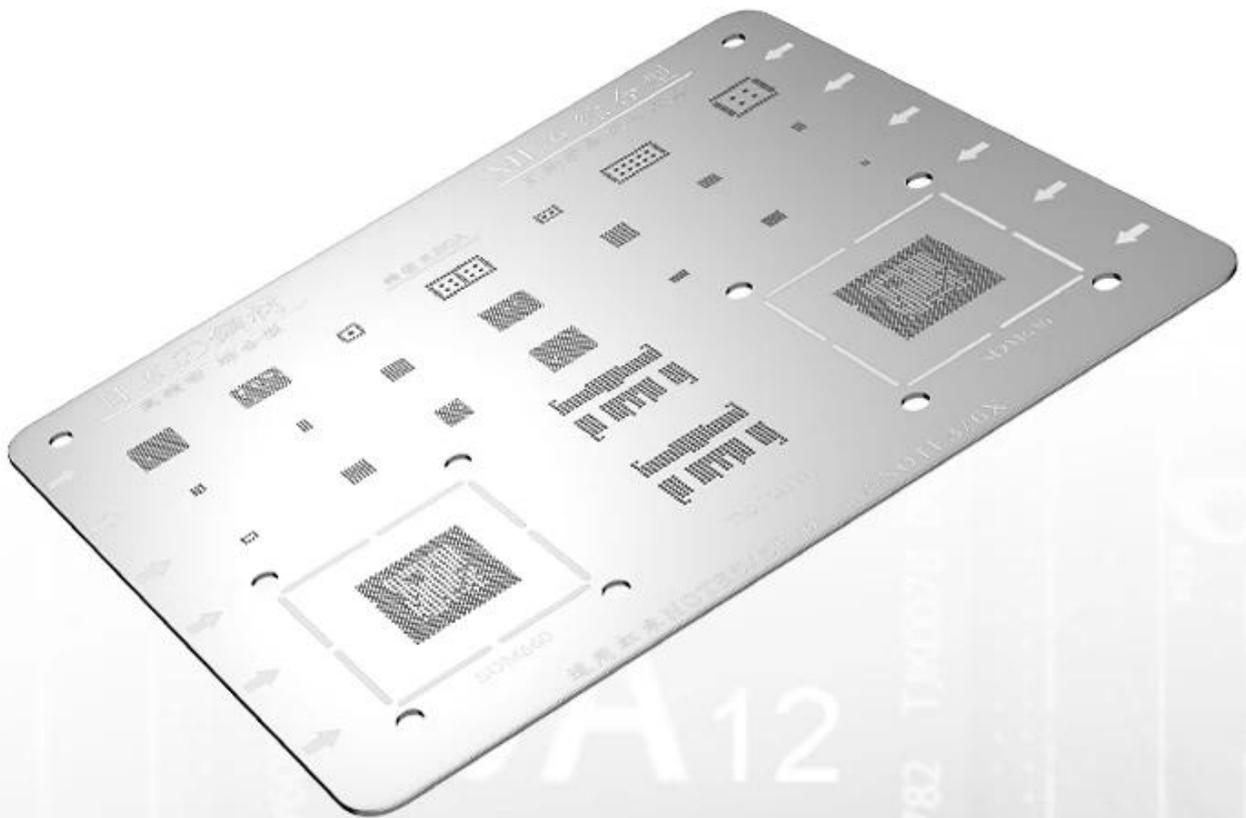
Adecuado para iPhone / Ipad

100 nuevo y de alta calidad

Nota: A veces, la fábrica actualiza la plantilla BGA Reballing, el tamaño puede ser diferente, pero la función es la misma.

REBALLING STENCIL

— REDMI/MI CPU series —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN

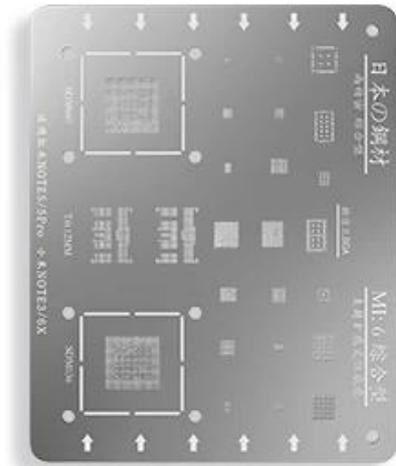


PRECISE ALIGNMENT



SQUARE HOLE

Product Usage



MATERIAL	Imported steel
BRAND	BESTOOL
PRODUCT NAME	Reballing Stencil
WEIGHT	7g
TYPE	Precise alignment Strong toughness Non-stick ti

▼ CHARACTERISTICS

This product is used for BGA tinning repair of the REDMI/MI series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

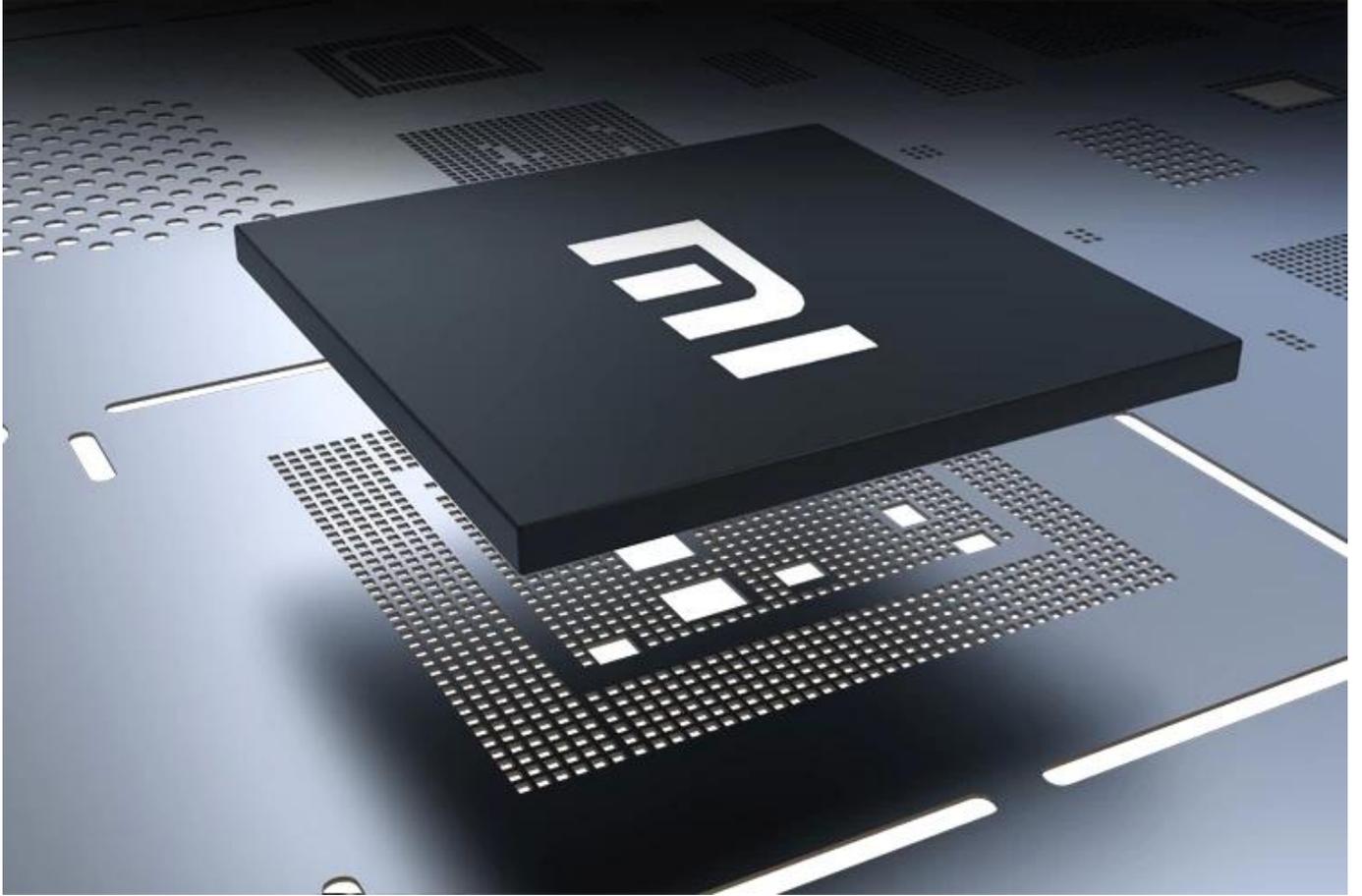


IMPORTED STEEL

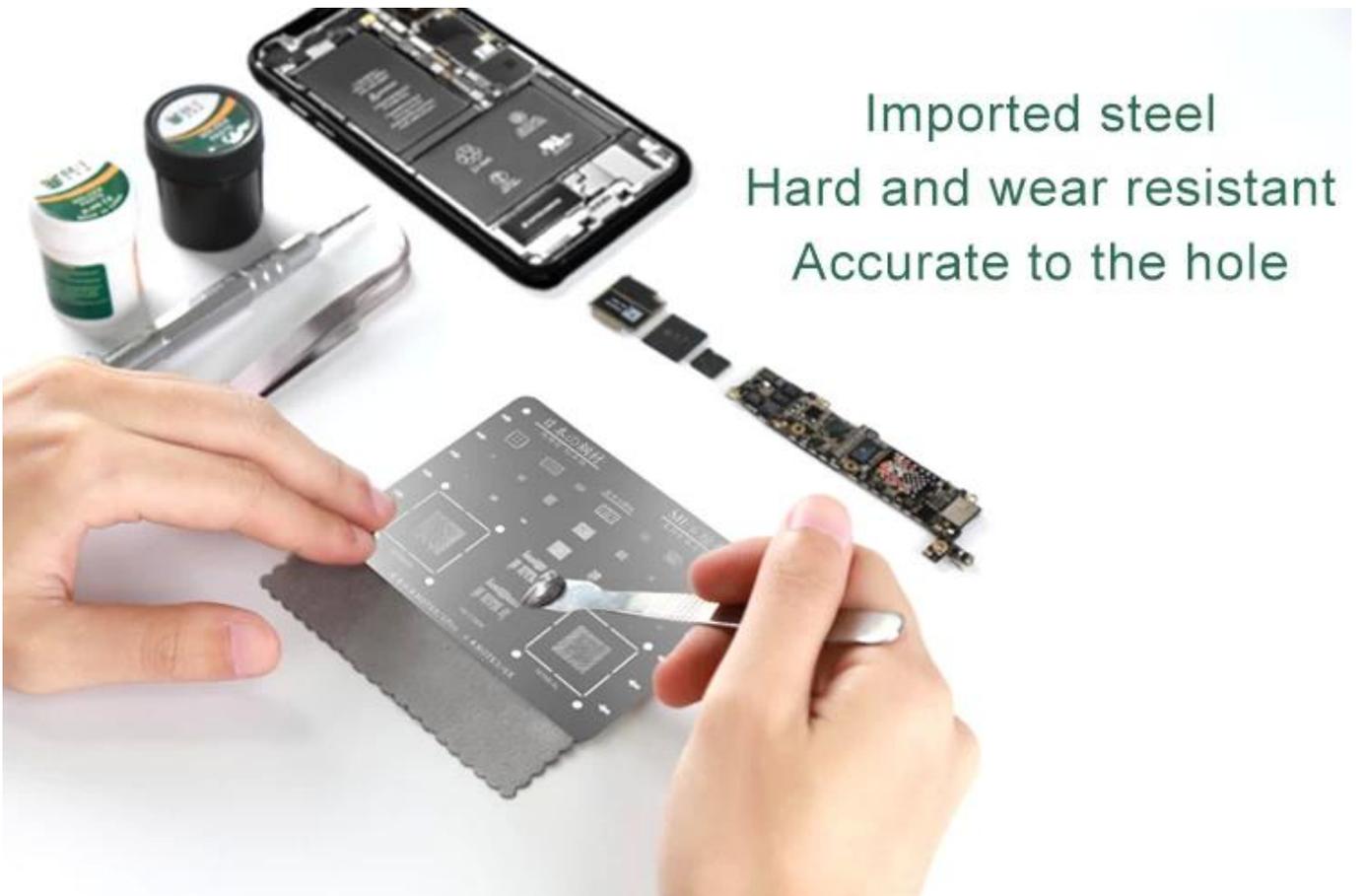
HIGH TOUGHNESS

GOOD PRODUCTS ARE NOT ONLY
EXCELLENT FORGING PROCESSES,
BUT THE REAL CORE LIES IN THE
SELECTION OF DELICATE MATERIALS.

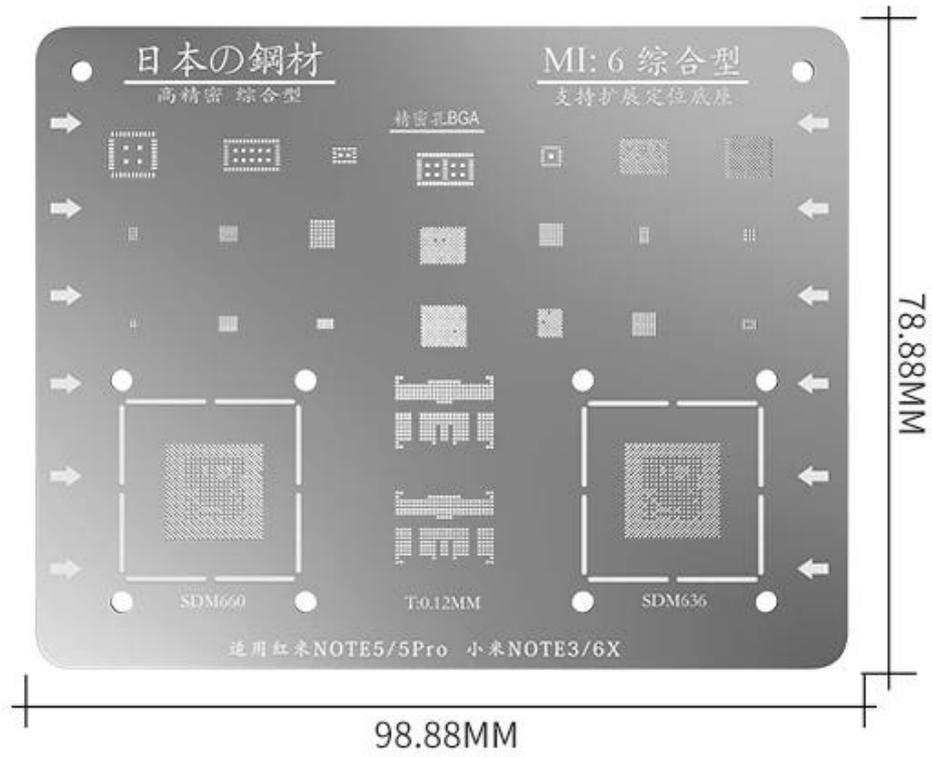
Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"



Imported steel
Hard and wear resistant
Accurate to the hole



PRODUCT SIZE



Thin to 0.12mm

Precise die-casting **form heating**



